

PACKAGE STRUCTURE FOR OPTICAL IMAGE SENSING INTEGRATED CIRCUITS

Abstract

A package structure for optical image sensing devices is disclosed. The package structure includes an image sensing integrated circuit chip having a light receiving side and a backside. The image sensing integrated circuit chip has a light sensing area on the light receiving side. A plurality of light sensing devices are arranged in the light sensing area for converting incident light into electrical signals. A plurality of bonding pads are arranged along one or two sides of the light sensing area. Black sealing glue is asymmetrically coated on the outskirts of the light sensing area. The black sealing glue has at least two coating widths. A glass lid is glued over the light sensing area with the sealing glue.